

Title (en)
DISTRIBUTION SYSTEM FOR A PROCESS FLUID FOR CHEMICAL AND/OR ELECTROLYTIC SURFACE TREATMENT OF A SUBSTRATE

Title (de)
VERTEILUNGSSYSTEM FÜR EINE PROZESSFLÜSSIGKEIT ZUR CHEMISCHEN UND/ODER ELEKTROLYTISCHEN
OBERFLÄCHENBEHANDLUNG EINES SUBSTRATS

Title (fr)
SYSTÈME DE DISTRIBUTION D'UN FLUIDE DE TRAITEMENT POUR TRAITEMENT DE SURFACE CHIMIQUE ET/OU ÉLECTROLYTIQUE
D'UN SUBSTRAT

Publication
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Application
EP 20160190 A 20200228

Priority
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Abstract (en)
The invention relates to a distribution system for a process fluid for chemical and/or electrolytic surface treatment of a substrate, a distribution method for a process fluid for chemical and/or electrolytic surface treatment of a substrate and a data processing device. The distribution system for a process fluid for chemical and/or electrolytic surface treatment of a substrate comprises a distribution body and a shield element. The distribution body comprises a plurality of openings for the process fluid. The shield element is configured to at least partially cover at least one of the plurality of openings to limit a flow of the process fluid through the distribution body.

IPC 8 full level
C25D 5/08 (2006.01); **C25D 17/00** (2006.01); **C25D 21/12** (2006.01)

CPC (source: EP KR US)
C23C 18/1628 (2013.01 - KR); **C25D 5/08** (2013.01 - EP KR US); **C25D 17/008** (2013.01 - EP KR US); **C25D 21/12** (2013.01 - EP KR US)

Citation (applicant)
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CN114630927A; WO2023232420A1

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AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

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